### REMARKS

This application is amended in a manner to place it in condition for allowance.

### Status of the Claims

Claim 1 is amended for clarity.

Claim 9 is new. Support may be found, for example, in the [0066] of the specification.

Claims 1, 3, 4, 6, 8 and 9 remain pending.

# Claim Interpretation

Claim 1 is amended to clarify the molecular weights.

### Claim Rejections-35 USC §103

Claims 1, 3, 4, 6 and 8 were rejected under 35 USC \$103(a) as being unpatentable over IKENO et al. US 2004/0028917(IKENO) in view of a Gelest technical bulletin (GELEST), further in view of FILAS et al. US Pat. 5,217,811 (FILAS). This rejection is respectively traversed for the reasons that follow.

IKENO was again offered for teaching curable organoopolysiloxane compositions comprising alkenyl-substituted polysiloxane, an organohydrogenpolysiloxane and an addition catalyst.

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GELEST was again offered for suggesting the claimed  $\mbox{molecular weights}$ .

FILAS was offered for teaching phenyl groups in a silicon-containing polymer.

However, the combination does not render obvious claims 1, 3, 4, 6 and 8 or new claim 9.

As disclosed at paragraph [0007] of the present specification, the object of the present invention is to provide a silicon containing curing composition excellent in storage stability, handling properties, and curing properties, a cured product of which is excellent in heat resistance and flexibility.

As further described at paragraph [0064] of the present specification, the present inventors have found out that the total content of the aryl group and the arylene group of the total silicon containing polymer(s) of the silicon containing composition is heavily influential on the heat resistance and handling properties of the composition. Based on this finding the present inventors have attained the present invention.

Contrarily, as acknowledged in the Official Action, IKENO is silent with regard to phenyl group content.

While FILAS indeed teaches a silicon containing polymer with a phenyl group content of 10 to 20 mol%, FILAS is not able to remedy this deficiency of IKENO for reference purposes.

 $\label{eq:with regard to phenyl group content, FILAS describes as} % \[ \frac{1}{2} \left( \frac{1}{2} \right) \left( \frac{1}{2} \left( \frac{1}{2} \right) \left( \frac{1}$ 

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"The index of refraction of the crosslinked siloxane copolymer may be varied by changing the phenyl group content. Preferred is a phenyl group content of 10 to 20 mole percent (remainder methyl groups) because this composition yields an index of refraction of the crosslinked siloxane copolymer most useful for device applications."

FILAS neither teaches nor suggests that the phenyl group content is influential to heat resistance and handling properties.

Therefore, it would not have been obvious for a skilled person in the art to adjust the content of phenyl group in the compositions of IKENO to 10 to 20 mol% in the pursuit of attaining the objective of the present invention.

Moreover, a skilled person in the art would never have realized that the phenyl group content of 10 to 20 mol% enables production of a silicon containing curing composition excellent in both heat resistance and flexibility.

Therefore, withdrawal of the rejection is respectfully requested.

## Conclusion

This application is in condition for allowance at the time of the next Official Action. Allowance and passage to issue on that basis is respectfully requested.

Should there be any matters that need to be resolved in the present application, the Examiner is respectfully requested to contact the undersigned at the telephone number listed below.

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The Commissioner is hereby authorized in this, concurrent, and future submissions, to charge any deficiency or credit any overpayment to Deposit Account No. 25-0120 for any additional fees required under 37 C.F.R. § 1.16 or under 37 C.F.R. § 1.17.

Respectfully submitted,

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